A METHOD OF ENCAPSULATING A

MICRO-ELECTROMECHANICAL (MEMS) DEVICE

ABSTRACT

[107] A method for encapsulating a micro-electromechanical (MEMS) device, the method comprising: providing a sacrificial layer arrangement over the MEMS device; providing a first encapsulation layer over the sacrificial layer arrangement, the first encapsulation layer defining at least one aperture; providing a second encapsulation layer over the at least one aperture, the second encapsulation layer being provided to allow removal of the sacrificial layer arrangement around the second encapsulation layer; and removing the sacrificial layer arrangement through the at least one aperture to allow the second encapsulation layer to cover the at least one aperture thereby encapsulating the MEMS device.

Figure 1